DYNAMICALLY ADJUSTABLE SLURRY FEED ARM FOR WAFER EDGE PROFILE IMPROVEMENT IN CMP

ABSTRACT

A dynamically adjustable slurry feed arm and method for adjusting the same in a CMP process including carrying out the CMP process for a predetermined period of time on a substrate comprising a polishing layer to remove a portion of a polishing layer; determining the thickness of the polishing layer at a plurality of predetermined measurement areas comprising at least a polishing layer peripheral portion and a polishing layer center portion; determining a desired subsequent dispensing position to equalize the thickness of the polishing layer; and, adjusting the slurry feed arm to the subsequent dispensing position such that the slurry is dispensed over the polishing pad at the subsequent dispensing position comprising one of closer to the polishing pad center portion and closer to the polishing pad peripheral portion.

FIG. 1A